

Disclosure to Promote the Right To Information

Whereas the Parliament of India has set out to provide a practical regime of right to information for citizens to secure access to information under the control of public authorities, in order to promote transparency and accountability in the working of every public authority, and whereas the attached publication of the Bureau of Indian Standards is of particular interest to the public, particularly disadvantaged communities and those engaged in the pursuit of education and knowledge, the attached public safety standard is made available to promote the timely dissemination of this information in an accurate manner to the public.

“जानने का अधिकार, जीने का अधिकार”

Mazdoor Kisan Shakti Sangathan

“The Right to Information, The Right to Live”

“पुराने को छोड़ नये के तरफ”

Jawaharlal Nehru

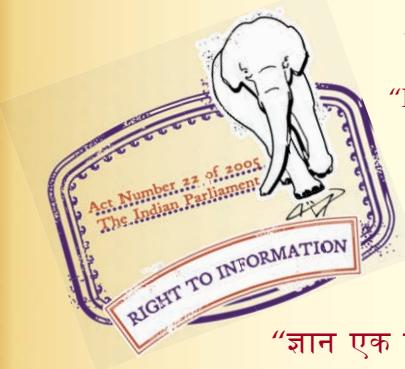
“Step Out From the Old to the New”

IS 5921-7 (1987): Metal Clad Base Materials for Printed Circuits for Use in Electronic and Telecommunication Equipment, Part 7: Epoxide Woven Glass Fabric Copper-Clad Laminated Sheet of Defined Flammability [LITD 5: Semiconductor and Other Electronic Components and Devices]

“ज्ञान से एक नये भारत का निर्माण”

Satyanaaran Gangaram Pitroda

“Invent a New India Using Knowledge”



“ज्ञान एक ऐसा खजाना है जो कभी चुराया नहीं जा सकता है”

Bhartṛhari—Nītiśatakam

“Knowledge is such a treasure which cannot be stolen”



BLANK PAGE



PROTECTED BY COPYRIGHT

IS : 5921 (Part 7) - 1987

Indian Standard

SPECIFICATION FOR

METAL CLAD BASE MATERIALS FOR
PRINTED CIRCUITS FOR USE IN ELECTRONIC
AND TELECOMMUNICATION EQUIPMENT

PART 7 EPOXIDE WOVEN GLASS FABRIC COPPER-CLAD
LAMINATED SHEET OF DEFINED FLAMMABILITY
(VERTICAL BURNING TEST)

UDC 621.313.619.419.8 : 669.386.8 : 621.3.049.75

© Copyright 1987

BUREAU OF INDIAN STANDARDS
MANAK BHAVAN, 9 BAHADUR SHAH ZAFAR MARG
NEW DELHI 110002

Indian Standard

SPECIFICATION FOR METAL CLAD BASE MATERIALS FOR PRINTED CIRCUITS FOR USE IN ELECTRONIC AND TELECOMMUNICATION EQUIPMENT

PART 7 EPOXIDE WOVEN GLASS FABRIC COPPER-CLAD LAMINATED SHEET OF DEFINED FLAMMABILITY (VERTICAL BURNING TEST)

Printed Circuits Sectional Committee, LTDC 17

Chairman

DR J. VAID

Representing

Peico Electronics & Electricals Ltd, Bombay

Members

SHRI M. A. GODBOLE (*Alternate to*
Dr J. Vaid)

SHRI R. ADINARAYANAN Ministry of Defence (LCSO)

SHRI K. RANGAPPA (*Alternate*)

SHRI AJIT KUMAR Electronic Component Industries Association
(ELCINA), New Delhi

SHRI GHANISHAM DASS (*Alternate*)

DR ASHOK KUMAR Partap Rajasthan Copper Foils and Laminates Ltd,
Jaipur

DR U. K. RATHI (*Alternate*)

SHRI R. K. BHATIA Department of Telecommunication, New Delhi

SHRI P. B. SAXENA (*Alternate*)

SHRI K. C. CHHABRA Ministry of Defence (R & D)

SHRI R. K. CHAKRAVARTI Department of Electronics, New Delhi

SHRI S. C. DUGGAL National Airports Authority, New Delhi

SHRI H. S. GREWAL (*Alternate*)

LT-COL B. C. MALHAN Ministry of Defence (DGI)

SHRI S. G. ADHKAR (*Alternate*)

DR M. KRISHNAN Bakelite Hylam Ltd, Hyderabad

SHRI VEDU MITTER Micropack Ltd, Bangalore

SHRI A. P. VASUDEVAN (*Alternate*)

SHRI K. NAGESH Bharat Electronics Ltd, Bangalore

SHRI J. SREE RAMACHANDRA

MURTHY (*Alternate*)

(*Continued on page 2*)

© Copyright 1987

BUREAU OF INDIAN STANDARDS

This publication is protected under the *Indian Copyright Act (XIV of 1957)* and reproduction in whole or in part by any means except with written permission of the publisher shall be deemed to be an infringement of copyright under the said Act.

(*Continued from page 1*)

<i>Members</i>	<i>Representing</i>
SHRI S. W. PATWARDHAN	Bombay Burmah Trading Corporation Ltd (Formica India Division), Pune
SHRI V. RANGANATHAN (<i>Alternate</i>)	
SHRI S. VENKATESWARA RAO	Hindustan Aeronautics Ltd, Hyderabad
SHRI N. C. NAGARAJAN (<i>Alternate</i>)	
REPRESENTATIVE	Hedge & Golay Ltd, Bangalore
REPRESENTATIVE	Research Designs & Standards Organization, Lucknow
SHRI M. K. SHARMA	Electronics Test & Development Centre, Chandigarh
SHRI R. K. SINGH	Electronics Corporation of India Ltd, Hyderabad
SHRI V. SUBRAMANIAN (<i>Alternate</i>)	
SHRI G. SUBBARAMAN	Indian Telephone Industries Ltd, Hyderabad
SHRI R. CHELLAPPA (<i>Alternate</i>)	
SHRI S. N. VYAS	Bhabha Atomic Research Centre, Bombay
SHRI HARCHARAN SINGH, Joint Director (Electronics)	Director General, BIS (<i>Ex-officio Member</i>)

Secretary

SHRI A. S. RAWAT
Deputy Director (Electronics), BIS

Indian Standard

SPECIFICATION FOR METAL CLAD BASE MATERIALS FOR PRINTED CIRCUITS FOR USE IN ELECTRONIC AND TELECOMMUNICATION EQUIPMENT

PART 7 EPOXIDE WOVEN GLASS FABRIC COPPER-CLAD LAMINATED SHEET OF DEFINED FLAMMABILITY (VERTICAL BURNING TEST)

0. FOREWORD

0.1 This Indian Standard (Part 7) was adopted by the Indian Standards Institution on 19 March 1987, after the draft finalized by the Printed Circuits Sectional Committee had been approved by the Electronics and Telecommunication Division Council.

0.2 This standard (Part 7) is to be used in conjunction with IS : 5921 (Part 1)-1983* which is necessary adjunct to this standard.

0.3 While preparing this standard, assistance has been derived from the following:

IEC Document 52 (Central office) 240 Draft — Revision of Publication 249-2 : Base Materials for Printed Circuits : Part 2 : Specifications; Specification No. 5 : Epoxide woven glass fabric copper clad laminated sheet of defined flammability (vertical burning test), International Electrotechnical Commission (IEC).

NEMA : Industrial laminated thermosetting products LI-1-1977, National Electrical Manufacturers' Association, USA.

0.4 For the purpose of deciding whether a particular requirement of this standard is complied with, the final value, observed or calculated, expressing the result of a test or analysis, shall be rounded off in accordance with IS : 2-1960†. The number of significant places retained in the rounded off value should be the same as that of the specified value in this standard.

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

†Rules for rounding off numerical values (*revised*).

1. SCOPE

1.1 This standard (Part 7) specifies the requirements for epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test) for use in printed wiring in telecommunication and allied electronic equipment.

2. TERMINOLOGY

2.1 For the purpose of this standard, the terms and definitions as given in IS : 1885 (Part 6)-1978* shall apply.

3. MATERIAL AND CONSTRUCTION

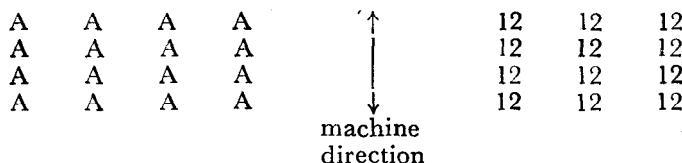
3.0 The sheet consists of an insulating base with metal foil bonded to one or both sides.

3.1 Insulating Base — The base material shall be epoxide resin bonded glass fabric laminate. Its flame resistance is defined in terms of flammability requirement specified in **8.3**.

3.2 Metal Foil — The base material shall be covered with copper foil as specified in IS : 10922-1984†.

4. MARKING

4.1 The marking shall be in red colour in accordance with **3** of IS : 5921 (Part 1)-1983‡. If letters or numbers are used, these shall be upright in the machine direction as shown below:



5. TESTS

5.1 The provisions of **4** of IS : 5921 (Part 1)-1983‡ shall apply except as modified by **5.1.1**. The methods of tests shall be as described in IS : 5921 (Part 1)-1983‡.

5.1.1 Acceptance Tests — In addition to the tests specified in **4.1.2** of IS : 5921 (Part 1)-1983‡, flammability test shall also be carried out as acceptance test. Sampling plans and acceptance levels may be agreed to between the purchaser and the supplier.

*Electrotechnical vocabulary: Part 6 Printed circuits (*first revision*).

†Specification for copper foil for use in the manufacture of copper-clad base materials.

‡Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

5.1.2 Routine Tests — The following tests may be carried out as routine tests:

- a) Visual examination, and
- b) Dimension and tolerances.

6. ELECTRICAL PROPERTIES

6.1 The electrical properties shall meet the requirements as given in Table 1.

TABLE 1 ELECTRICAL PROPERTIES

SL No.	PROPERTY	TEST METHOD [CLAUSE OF IS : 5921 (PART 1)-1983*]	REQUIREMENTS	
			5.1	As specified in IS : 10922-1984†
i)	Resistance of foil	5.1		
ii)	Surface resistance while in humidity chamber (optional)	5.2	10 000 MΩ, Min	
iii)	Surface resistance after recovery	5.2	50 000 MΩ, Min	
iv)	Volume resistivity while in humidity chamber (optional)	5.2	5 000 MΩ, Min	
v)	Volume resistivity after recovery	5.2	10 000 MΩ, Min	
vi)	Surface corrosion	5.7	No visible corrosion products in the gap	
vii)	Corrosion at the edge	5.8	Positive pole: Not worse than A/B Negative pole: Not worse than 1·4	
viii)	Relative permittivity after damp heat and recovery	5.4	The average value shall not exceed 5·5	
ix)	Dielectric dissipation factor after damp heat and recovery	5.4	The average value shall not exceed 0·035	
x)	Surface resistance of 125°C	5.2.4	1 000 MΩ, Min	
xi)	Volume resistivity at 125°C	5.2.4	1 000 MΩ, Min	

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

†Specification for copper foil for use in the manufacture of copper-clad base materials.

7. NON-ELECTRICAL PROPERTIES OF THE COPPER-CLAD SHEET

7.1 Surface Finish of the Copper-Clad Face

7.1.1 The copper-clad face shall be free from blisters, wrinkles, pinholes, deep scratches, pits and resin. Any discolouration or contamination shall be readily removed with a hydrochloric acid solution of density 1.02 g/cm³ or with a suitable organic solvent. The surface shall be inspected in accordance with 6.2 of IS : 5921 (Part 1)-1983*. The surface finish of the copper-clad face shall be such as not to conceal imperfections.

7.1.2 The surface of the copper foil shall be free from scratches of depth greater than 0.010 mm or 1/5 of the nominal thickness of the copper foil, whichever is the lower.

7.1.3 The total length of scratches of depth greater than 0.005 mm but not greater than 0.010 mm shall not exceed 1 m per square metre of the total area of the sheet under test.

7.1.4 The area of any one or number of pinholes in an area of 0.5 m² shall not exceed the area of a circle of diameter 0.125 mm.

7.1.5 No sheet shall have more imperfections of the types listed than those permitted by Table 2.

7.2 Thickness

7.2.1 The thickness of a sheet, including the metal foil, shall not depart at any point from the nominal thickness by more than the appropriate value below:

Nominal Thickness mm	Deviations	
	Coarse mm	Close mm
0.5	—	±0.07
0.7	±0.15	±0.09
0.8	±0.15	±0.09
1.0	±0.17	±0.11
1.2	±0.18	±0.12
1.5	±0.20	±0.14
1.6	±0.20	±0.14
2.0	±0.23	±0.15
2.4	±0.25	±0.18
3.2	±0.30	±0.20
6.4	±0.56	±0.30

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

TABLE 2 TYPES, SIZES AND PERMITTED NUMBERS OF IMPERFECTIONS
(Clause 7.1.5)

SL No.	TYPE	SIZE (LENGTH, UNLESS OTHERWISE INDICATED)		NUMBER OF IMPERFECTIONS PERMITTED	
		Above mm	Not Above mm	In Any Sheet of Area About 1 m ²	In Any Area of 300 mm × 300 mm
(1)	(2)	(3)	(4)	(5)	(6)
i) Inclusions	—	0·1	0·25	Any number	Any number
	0·1	0·25	—	30	4
	0·25	—	—	0	0
ii) Indentations	—	0·25	0·25	Any number	Any number
	0·25	1·25	1·25	13†	3*
	1·25	3·0 or width 1·0	3·0 or width 1·0	3†	1*
	3·0 or width 1·0	—	—	0	0
iii) Bumps	—	0·1	0·1	Any number	Any number
	0·1	4·0 or height 0·1	height 0·1	10	2
	4·0 or height 0·1	—	—	0	0
iv)	Wrinkles/blisters	Of any size	—	0	0

NOTE 1 — For sheets of 1 m² or greater, the values of the fifth column apply for any area of 1 m²; for the same sheets in any area of 300 mm × 300 mm, however, the values of the sixth column apply. For sheets smaller than 1 m², the sixth column applies for any area of 300 mm × 300 mm.

NOTE 2 — For out panels, smaller sizes and other numbers of imperfections may be agreed upon between purchaser and supplier.

*The total for these sizes of indentations is 3.

†The total for these sizes of indentations is 13.

7.2.2 The thickness and tolerances do not apply to the outer 25 mm of the trimmed laminated sheet as supplied by the vendor. At least 90 percent of the area, regardless of size, shall be within the tolerances given, and at no point shall the thickness vary from the nominal by a value greater than 125 percent of the specified tolerance.

7.2.3 For any nominal thickness within the range of nominal thickness 0·5 to 6·4 mm, which is not given in the table of nominal thickness and corresponding deviations, the deviation applicable to the thickness shall be that for the next greater nominal thickness given in the table.

7.3 Bow and Twist — The bow and twist requirements are specified in Table 3.

TABLE 3 BOW AND TWIST

(Clause 7.3)

SL No.	PROPERTY	TEST METHOD		REQUIREMENTS
		[CLAUSE OF IS : 5921 (PART 1)-1983*]	(3)	
(1)	(2)	(3)	(4)	
i)	Bow	6.6	Shall not exceed the value given by the formula $d (L/1\ 000)^2$ mm, where: L is the length of the straight edge in millimetres and d is as given in Table 4	
ii)	Twist	6.7	Shall not exceed the value given by the formula $d (L/1\ 000)^2$ mm, where: L is the distance in millimetres between the corner of the sheet not in contact with the horizontal surface and the diagonally opposite corner, and d is as given in Table 4	

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

TABLE 4 PARAMETERS RELATED TO BOW AND TWIST

(Table 3, Col 4)

SL No.	NOMINAL THICKNESS (mm)	COPPER FOIL ON ONE SIDE, d			COPPER FOIL ON BOTH SIDES, d , BOW AND TWIST NOT OVER 70 μm †	
		Bow		Not Over 35 μm^*		
		Not Over 35 μm^*	Up to 70 μm^{\dagger}			
(1)	(2)	(3)	(4)	(5)	(6)	
i)	0.5 to 1.2	34	46	30	15	
ii)	Over 1.2 to 1.6	23	38	25	15	
iii)	Over 1.6 to 6.4	11	20	15	10	

NOTE 1 — Limits for laminates clad with foil of nominal thickness greater than 70 μm (610 g/m²) shall be subject to arrangement between purchaser and supplier.

NOTE 2 — The requirements for bow and twist apply only to sheet sizes as manufactured and to cut pieces having neither length nor width less than 460 mm.

*35 μm (305 g/m²).†70 μm (610 g/m²).

7.4 Properties Related to the Copper Foil Bond — These properties are specified in Table 5.

7.5 Punching and Machining — Methods of test for punching properties and requirements for these are matters for agreement between purchaser and supplier.

TABLE 5 PROPERTIES OF COPPER FOIL BOND
(Clause 7.4)

SL No.	PROPERTY	TEST METHOD [CLAUSE OF IS : 5921 (PART 1)- 1983*]	REQUIREMENTS
(1)	(2)	(3)	(4)
i)	Pull-off strength	6.11	Not less than 60 N
ii)	Peel strength after heat shock of 10 s by the methods a or b or 5 s by method c	6.10.4 (a, b or c)	Not less than 1.4 N/mm
iii)	Peel strength after dry heat at 100°C	6.10.5	
iv)	Peel strength after exposure to solvent vapour 1:1:1 trichlorethylene	6.10.6	No blistering or delami- nation
	NOTE — For solvents other than trichlorethylene, re- quirements shall be agreed upon between purchaser and supplier		
v)	Peel strength after simulated plating	6.10.7	Not less than 0.8 N/mm
vi)	Peel strength at high tem- perature (260°C)	6.10.8	Not less than 0.075 N/mm
	NOTE — In case of diffi- culties due to breaking foil or reading range the device for measuring the force the measurement of the peel strength at high temperature may be carried out using conductor widths larger than 3 mm		
vii)	Blistering after 20 s heat shock	6.9	No delamination or blistering

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

7.6 Solderability

7.6.1 When the sheet is tested as specified in **6.8** of IS : 5921 (Part 1)-1983* and in accordance with the times and temperatures specified below, the soldered areas shall be covered with a smooth and bright

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

solder coating. Scattered imperfections, such as pin-holes, shall not occur on more than 5 percent of the surface and shall not be concentrated in one area. At least six specimens out of each batch of ten shall pass the test.

a) *Wetting*

<i>Nominal Thickness (mm)</i>	<i>Thickness of Copper (μm)</i>	<i>Maximum Wetting Time (s)</i>	<i>Temperature (°C)</i>
0·5 up to 1·6	35 (305 g/m ²)	2	235 + 5 - 0
Over 1·6 up to 6·4	35 (305 g/m ²)	3	235 + 5 - 0
0·5 up to 6·4	70 (610 g/m ²)	3	235 + 5 - 0

b) *Dewetting*

Test specimens shall remain in contact with the molten solder for 5 ± 1 s at $260 \pm 5^\circ\text{C}$.

NOTE — For thicknesses of copper greater than $70 \mu\text{m}$ (610 g/m^2), the wetting and dewetting time shall be agreed between purchaser and supplier.

8. NON-ELECTRICAL PROPERTIES OF THE BASE MATERIAL AFTER COMPLETE REMOVAL OF THE COPPER FOIL

8.1 Appearance of the Base Material — The base material shall be substantially free from pits, holes, scratches, porosity and resin inclusions and substantially uniform in colour. A small amount of irregular variation of colour is permissible.

8.2 Flexural Strength — This test is applicable to sheets not thinner than 1·0 mm of nominal thickness. The test should be carried out in accordance with 7.1 of IS : 5921 (Part 1)-1983*. The flexural strength shall not be less than 30 000 N/cm.

8.3 Flammability — The vertical burning test shall be carried out in accordance with 7.2.3 of IS : 5921 (Part 1)-1983*. The following requirements shall be met:

- a) No specimen shall burn with flaming combustion for more than 30 s after either applications of test flame;
- b) The total flaming combustion time shall not exceed 250 s for each set of 5 specimens;

*Specification for metal-clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

- c) No specimen shall burn with flaming or glowing combustion up to the holding clamp;
- d) No specimen shall burn with glowing combustion which persists beyond 60 s after the second removal of the test time; and
- e) The material shall not drip flaming particles which ignite the tissue paper.

8.4 Water Absorption — It shall be measured in accordance with 7.3 of IS : 5921 (Part 1)-1983* and shall meet the following requirement. In case of thicknesses not included below, the requirement for next greater thickness shall apply:

<i>Nominal Thickness</i> mm	mg (Max)
0·5	20
0·7	20
0·8	20
1·0	20
1·2	20
1·5	20
1·6	20
2·0	24
2·4	22
3·2	25
6·4	32

9. PACKAGING

9.1 The sheets shall be adequately packed and protected in cases or crates to avoid damage in transit and during storage.

*Specification for metal clad base materials for printed circuits for use in electronic and telecommunication equipment: Part 1 General requirements and tests (*first revision*).

INTERNATIONAL SYSTEM OF UNITS (SI UNITS)

Base Units

QUANTITY	UNIT	SYMBOL
Length	metre	m
Mass	kilogram	kg
Time	second	s
Electric current	ampere	A
Thermodynamic temperature	kelvin	K
Luminous intensity	candela	cd
Amount of substance	mole	mol

Supplementary Units

QUANTITY	UNIT	SYMBOL
Plane angle	radian	rad
Solid angle	steradian	sr

Derived Units

QUANTITY	UNIT	SYMBOL	DEFINITION
Force	newton	N	1 N = 1 kg.m/s ²
Energy	joule	J	1 J = 1 N.m
Power	watt	W	1 W = 1 J/s
Flux	weber	Wb	1 Wb = 1 V.s
Flux density	tesla	T	1 T = 1 Wb/m ²
Frequency	hertz	Hz	1 Hz = 1 c/s (s ⁻¹)
Electric conductance	siemens	S	1 S = 1 A/V
Electromotive force	volt	V	1 V = 1 W/A
Pressure, stress	pascal	Pa	1 Pa = 1 N/m ²

BUREAU OF INDIAN STANDARDS

Headquarters:

Manek Bhavan, 9 Bahadur Shah Zafar Marg, NEW DELHI 110002

Telephones : 331 0131 331 1375

Telegrams : Mansksanstha
(Common to all Offices)

Regional Offices:

Telephone

*Western : Manakalaya, E9 MIDC, Marol Andheri (East) 6 32 92 95
BOMBAY 400093

†Eastern : 1/14 C. I. T. Scheme VII M. V. I. P. Road, 36 24 99
Maniktola, CALCUTTA 700054

Northern : SCO 445-446, Sector 35-C { 2 18 43
CHANDIGARH 160036 { 3 16 41

Southern : C. I. T. Campus, MADRAS 600113 { 41 24 42
{ 41 25 19
{ 41 29 18

Branch Offices:

'Pushpak', Nurmohamed Shaikh Marg, Khanpur { 2 63 48
AHMADABAD 380001 { 2 63 49

F Block, Unity Bldg, Narasimharaja Square, 22 48 05
BANGALORE 560002

Gangotri Complex, 5th Floor, Bhadbhada Road, 6 67 16
T. T. Nagar, BHOPAL 462003

Plot No. 82/83, Lewis Road, BHUBANESHWAR 751002 5 36 27

53/5 Ward No. 29, R. G. Barua Road, 5th Byelane, —
GUWAHATI 781003

5-8-58C L.N. Gupta Marg, HYDERABAD 500001 23 10 83

R14 Yudhister Marg, C Scheme, JAIPUR 302006 { 6 34 71
{ 6 98 32

117/418 B Sarvodaya Nagar, KANPUR 208005 { 21 68 76
{ 21 82 92

Patliputra Industrial Estate, PATNA 800013 6 23 05

Hantex Bldg (2nd Floor), Ry Station Roed, 52 27
TRIVANDRUM 695001

Inspection Office (With Sale Point):

Institution of Engineers (India) Building, 1332 Shivaji Nagar, 5 24 35
PUNE 411005

*Sales Office in Bombay is at Novelty Chambers, Grant Roed, 89 65 28
BOMBAY 400007

†Sales Office in Calcutta is at 5 Chowinghee Approach 27 68 00
P.O. Princep Street, CALCUTTA 700072